imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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LIXYS

= 170 A

= 600 V

IGBT Modules Sixpack

Short Circuit SOA Capability Square RBSOA

Preliminary data





See outline drawing for pin arrangement

€switching frequency up to 30 kHz €square RBSOA, no latch up €high short circuit capability €positive temperature coefficient for

€MOS input, voltage controlled €ultra fast free wheeling diodes €solderable pins for PCB mounting €package with copper base plate

€NPT IGBT technology
€low saturation voltage
€low switching losses

easy parallelling

V_{CE(sat) typ.} **= 2.0 V**

Features

I_{C25} V_{CES}

IGBTs

Symbol	Conditions	Maximum Ra	Maximum Ratings		
V _{CES}	$T_{vJ} = 25^{\circ}C$ to $150^{\circ}C$	600	V		
V _{GES}		± 20	V		
I _{C25} I _{C80}	$T_{c} = 25^{\circ}C$ $T_{c} = 80^{\circ}C$	170 115	A A		
RBSOA	$V_{GE} = \pm 15 \text{ V}; \text{ R}_{G} = 1.5 \Omega; \text{ T}_{VJ} = 125^{\circ}\text{C}$ Clamped inductive load; L = 100 µH	$\begin{array}{l} I_{\text{CM}} = & 300 \\ V_{\text{CEK}} \leq V_{\text{CES}} \end{array}$	A		
t _{sc} (SCSOA)	$V_{CE} = V_{CES}; V_{GE} = \pm 15 \text{ V}; \text{ R}_{G} = 1.5 \Omega; \text{ T}_{VJ} = 1$ non-repetitive	25°C 10	μs		
P _{tot}	$T_c = 25^{\circ}C$	515	W		

Symbol Conditions

Characteristic Values $(T_{yy} = 25^{\circ}C, \text{ unless otherwise specified})$

	(1,1) = 20 (min.	typ.	max.	
V _{CE(sat)}	$I_{c} = 150 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		2.0 2.3	2.5	V V
V _{GE(th)}	$I_{c} = 3 \text{ mA}; V_{ge} = V_{ce}$	4.5		6.5	V
I _{ces}	$V_{_{CE}} = V_{_{CES}}; V_{_{GE}} = 0 \text{ V}; \text{T}_{_{VJ}} = \begin{array}{c} 25^{\circ}\text{C} \\ \text{T}_{_{VJ}} = 125^{\circ}\text{C} \end{array}$		1.1	1.5	mA mA
I _{ges}	$V_{ce} = 0 \text{ V}; V_{ge} = \pm 20 \text{ V}$			400	nA
$\begin{array}{c} t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ E_{on} \\ E_{off} \end{array}$	$\left. \begin{array}{l} \text{Inductive load, } T_{_{VJ}} = 125^{\circ}\text{C} \\ \text{V}_{_{CE}} = 300 \text{ V; } \text{I}_{_{C}} = 150 \text{ A} \\ \text{V}_{_{GE}} = \pm15 \text{ V; } \text{R}_{_{G}} = 1.5 \Omega \end{array} \right.$		125 30 225 35 2.3 4.6		ns ns ns mJ mJ
C _{ies} Q _{Gon}	$V_{_{CE}} = 25 \text{ V}; V_{_{GE}} = 0 \text{ V}; f = 1 \text{ MHz}$ $V_{_{CE}} = 300 \text{V}; V_{_{GE}} = 15 \text{ V}; I_{_{C}} = 150 \text{ A}$		6.5 520		nF nC
R _{thJC}	(per IGBT)			0.24	K/W

€space savings €reduced protection circuits €package designed for wave soldering

Advantages

Typical Applications

€AC motor control
€AC servo and robot drives
€power supplies

LIXYS

Equivalent Circuits for Simulation

Diodes					
Symbol	Conditions	Maximum Rating	Maximum Ratings		
I _{F25}	$T_c = 25^{\circ}C$	210	A		
I _{F80}	$T_c = 80^{\circ}C$	130	A		

Symbol	Conditions	Ch min.	aracteristic Values typ. max.		
V _F	$I_{_{\rm F}} = 150 \text{ A}; \text{ V}_{_{\rm GE}} = 0 \text{ V}; \text{ T}_{_{\rm VJ}} = \begin{array}{c} 25^{\circ}\text{C} \\ \text{T}_{_{\rm VJ}} = 125^{\circ}\text{C} \end{array}$		1.9 1.4	2.0	V V
l _{em} t _{rr}	$\left. \begin{array}{l} I_{_{\rm F}} = 150 \text{ A}; di_{_{\rm F}}/dt = -750 \text{ A}/\mu s; T_{_{\rm VJ}} = 125^\circ C \\ V_{_{\rm R}} = 300 \text{ V}; V_{_{\rm GE}} = 0 \text{ V} \end{array} \right. \label{eq:VJ}$		37 100		A
R _{thJC}	(per diode)			0.41 K/\	N

Module				
Symbol	Conditions	Maximum Ratings		
T _{vj}	operating	-40+125	°C	
T _{JM}		+150	°C	
T _{stg}		-40+125	°C	
VISOL	$I_{ISOL} \le 1 \text{ mA}; 50/60 \text{ Hz}$	2500	٧~	
M _d	Mounting torque (M5)	3 - 6	Nm	

Symbol	Conditions	Characteristic Values min. typ. max.		
R _{pin-chip}			1.8	mΩ
d _s d _A	Creepage distance on surface Strike distance in air	10 10		mm mm
R _{thCH}	with heatsink compound		0.01	K/W
Weight			300	g



$$C_{th1} = 0.21 J/K; R_{th1} = 0.317 K/W$$
$$C_{th2} = 1.28 J/K; R_{th2} = 0.093 K/W$$

Dimensions in mm (1 mm = 0.0394")



IXYS reserves the right to change limits, test conditions and dimensions.